



Form PTO-1449

U.S. Application No.: 10/725,933

Attorney Docket No.: HK9225US (formerly 25857)

IDS Filed: November 9, 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

INFORMATION DISCLOSURE CITATION

In re application of: Yang et al.

Confirmation No.: 4487

Serial No.: 10/725,933

Group No.: 2891

Filed: December 3, 2003

Examiner: David A. Zarneke

For: FAN OUT TYPE WAFER LEVEL PACKAGE STRUCTURE AND METHOD OF THE SAME

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Foreign Patent Documents

Examiner Initials	Document Number	Country	Date of Publication	Class	Translation (Yes/No)
<u>DAZ</u>	177,766	Taiwan	09/05/2003	H01L23/02	Yes
<u>DAZ</u>	Abstract of Taiwan Patent Publication No. TW 531854B, published 05/11/2003.				

Examiner:

Date Considered:

/David Zarneke/

12/03/2006

****Examiner:** Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.